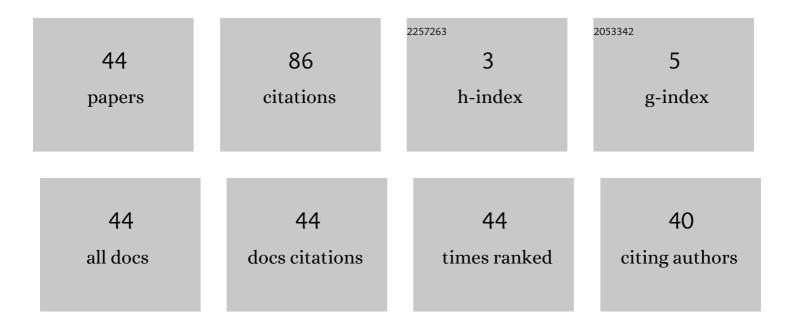
Zaliman Sauli

List of Publications by Year in descending order

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ΖΑΓΙΜΑΝ ΚΑΠΠ

| # | Article | IF | CITATIONS |
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| 1 | Interaction of Surface Roughness and Copper Ball Adhesion Using Shearing Simulation. , 2012, , . | | 11 |
| 2 | Shear Stress Analysis Study Using Surface Morphology Correlation with Aluminium Ball Adhesion. , 2012, , . | | 10 |
| 3 | Shearing Speed Induced Stress Comparison on Gold and Copper Ball Interconnection. , 2012, , . | | 9 |
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| 6 | Gold Ball Shear Stress Analysis on Different Surface Morphology. , 2012, , . | | 6 |
| 7 | A review: Application of adhesive bonding on semiconductor interconnection joints. AIP Conference Proceedings, 2017, , . | 0.3 | 6 |
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| 9 | Gold and Copper Ball Bond Shear Stress Comparison At Different Shear Tool Heights. , 2012, , . | | 3 |
| 10 | Natural Heat Convection Analysis on Cylindrical Al Slug of LED. Applied Mechanics and Materials, 2014, 487, 536-539. | 0.2 | 3 |
| 11 | A review on solder reflow and flux application for flip chip. AIP Conference Proceedings, 2017, , . | 0.3 | 3 |
| 12 | A short review on thermosonic flip chip bonding. AIP Conference Proceedings, 2017, , . | 0.3 | 3 |
| 13 | Aluminium Surface Grain Size Analysis on RIE Treatment. Applied Mechanics and Materials, 0, 404, 67-71. | 0.2 | 2 |
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| 16 | Grain Size Analysis on Ba _{0.65} Sr _{0.35} TiO ₃ Thin Films Using Design of Experiment. Advanced Materials Research, 0, 896, 211-214. | 0.3 | 2 |
| 17 | Operating Temperature Analysis of LED with Cylindrical Cu Slug. Applied Mechanics and Materials, 0, 487, 145-148. | 0.2 | 2 |
| 18 | Finite element modelling of thermal performance of LED lamp using open source software - salome and elmer. , 2017, , . | | 2 |

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| 19 | CORE NUCLEUS DYNAMICS IN \hat{I} HYPERNUCLEI. International Journal of Modern Physics E, 2009, 18, 1302-1312. | 0.4 | 1 |
| 20 | LED Heat Dissipation Analysis Using Composite Based Cylindrical Slug. Advanced Materials Research, 2014, 893, 803-806. | 0.3 | 1 |
| 21 | Electrode design and planar uniformity of anodically etched small area porous silicon. , 2009, , . | | Ο |
| 22 | 5mm × 5mm Sized Slug on High Power LED Stress and Junction Temperature Analysis. Applied Mechanics and Materials, 0, 404, 460-464. | 0.2 | 0 |
| 23 | Shear Ram Speed Analysis for Gold Wire Bond Shear Test. , 2013, , . | | Ο |
| 24 | Finite Element Analysis on Sn-3.9Ag-0.6Cu and Sn-3.5Ag-0.7Cu Using Different Shearing Height. , 2013, , . | | 0 |
| 25 | Bump Height at Low Temperature Analysis. Applied Mechanics and Materials, 0, 404, 77-81. | 0.2 | Ο |
| 26 | Shear Speed Analysis on Sn-3.9Ag-0.6Cu Solder. Applied Mechanics and Materials, 0, 404, 72-76. | 0.2 | 0 |
| 27 | Convection Condition Variation Analysis on Thermal Dissipation of High Power Single Chip LED. Advanced Materials Research, 2014, 1082, 336-339. | 0.3 | 0 |
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| 32 | Main Effects Study on Plasma Etched Aluminium Metallization. Applied Mechanics and Materials, 0, 487, 195-198. | 0.2 | 0 |
| 33 | Chemical Bath Temperature Investigation for Electroless Nickel Immersion Gold. Advanced Materials Research, 0, 925, 96-100. | 0.3 | Ο |
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